


Full Material Declaration for attached parts list

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	Diotec Semiconductor AG DUNS number: 330866844 -, Kreuzmattenstr. 4, Heitersheim, B.-W., 79423, Germany Declarations authorised by Udo Steinebrunner, Product Manager, -

Declaration effective from: 06 December 2016 [Approved: 09 July 2025 10:23 GMT]

Individual materials in the part			Individual substances in each material		
Use/Location	Material Group	Max mass %	Substance	CAS Number	Max mass %
Chip (die)	Other inorganic materials	0.3%	Nickel REACH Article 67 Exemption	7440-02-0	2.25%
			Gold	7440-57-5	10.25%
			Polydimethyl siloxane	63148-62-9	25%
			Silicon	7440-21-3	62.5%
			Silver	7440-22-4	1.5%
Die attach	Lead and Lead alloys	0.1%	Tin	7440-31-5	3%
			Lead Exempt from other regulatory requirements EU RoHS Exemption 27 Exempt from other regulatory requirements	7439-92-1	95.5%
			Carbon black	1333-86-4	1%
Encapsulation	EP (Epoxy resin)	22.5%	Phenol, polymer with formaldehyde	9003-35-4	15%
			Formaldehyde, polymer with (chloromethyl)oxirane and 2-methylphenol	29690-82-2	20%
Leadfinish	Tin plating	2.7%	Quartz Exempt from other regulatory requirements	14808-60-7	64%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	74.4%	Tin	7440-31-5	100%
			Copper	7440-50-8	100%

Attached parts list

Part number	Part name
DO-15 (DCN) H-Free	Diode axial